

AMENDMENTS TO THE CLAIMS

1. - 11. (Cancelled)

12. (Currently Amended) A semiconductor package comprising:

a substrate having an upper surface, a lower surface, and an edge region disposed between said upper and lower surfaces, said edge including a first cut portion and a second broken portion comprising a sheared portion.

13. (Previously Presented) A semiconductor package as defined in claim 12 wherein said cut portion further comprises a sawn portion.

14. (Previously Presented) A semiconductor package as defined in claim 12 wherein said cut portion further comprises a scribed portion.

15. (Previously Presented) A semiconductor package as defined in claim 12 wherein said cut portion further comprises a chemically etched portion.

16. (Previously Presented) A semiconductor package as defined in claim 12 wherein said cut portion further comprises a milled portion.

17– 29. (Cancelled)